

# HRU0302A

## Silicon Schottky Barrier Diode for Rectifying

REJ03G0151-1000  
Rev.10.00  
Mar 31, 2006

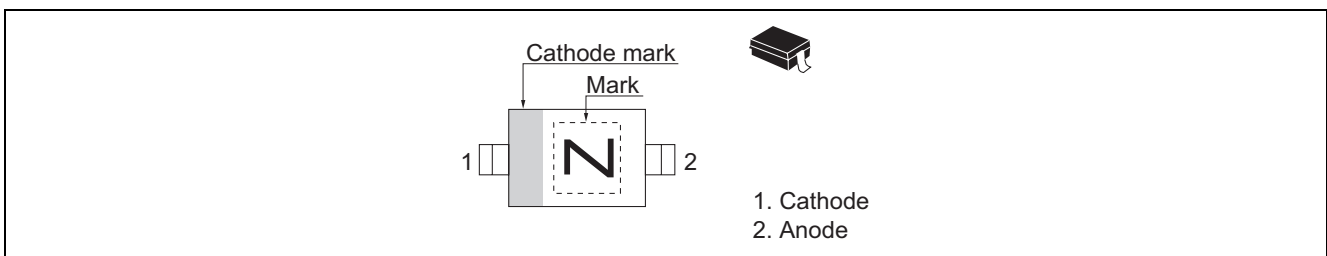
### Features

- Low forward voltage drop and suitable for high efficiency rectifying.
- Ultra small Resin Package (URP) is suitable for high density surface mounting and high speed assembly.

### Ordering Information

Type No.	Laser Mark	Package Name	Package Code (Previous Code)
HRU0302A	Z	URP	PTSP0002ZA-A

### Pin Arrangement



## Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Repetitive peak reverse voltage	$V_{RRM}^{*1}$	20	V
Average rectified current	$I_O^{*1}$	300	mA
Non-Repetitive peak forward surge current	$I_{FSM}^{*2}$	3	A
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-55 to +125	°C

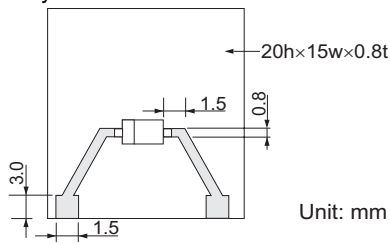
Notes: 1. See from Fig.4 to Fig.6.  
 2. 10 ms sine wave 1 pulse.

## Electrical Characteristics

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Forward voltage	$V_F$	—	—	0.40	V	$I_F = 300 \text{ mA}$
Reverse current	$I_R$	—	—	100	$\mu\text{A}$	$V_R = 20 \text{ V}$
Capacitance	C	—	70	—	pF	$V_R = 0 \text{ V}, f = 1 \text{ MHz}$
Thermal resistance	Rth(j-a)	—	440	—	°C/W	Polyimide board <sup>*1</sup>

Note: 1. Polyimide board



Main Characteristic

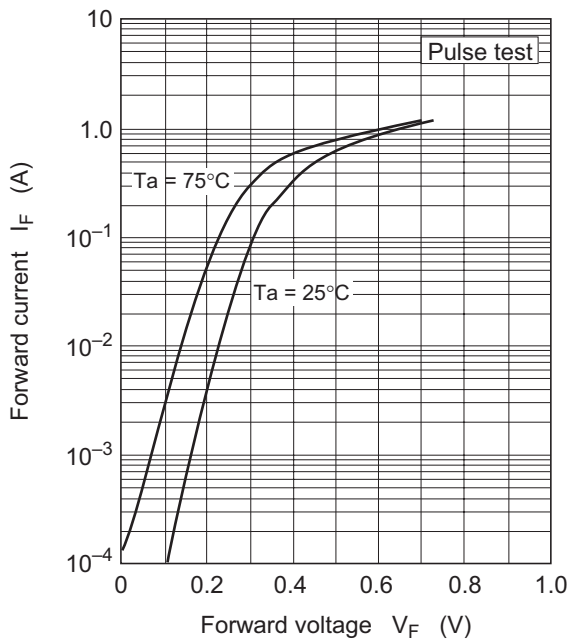


Fig.1 Forward current vs. Forward voltage

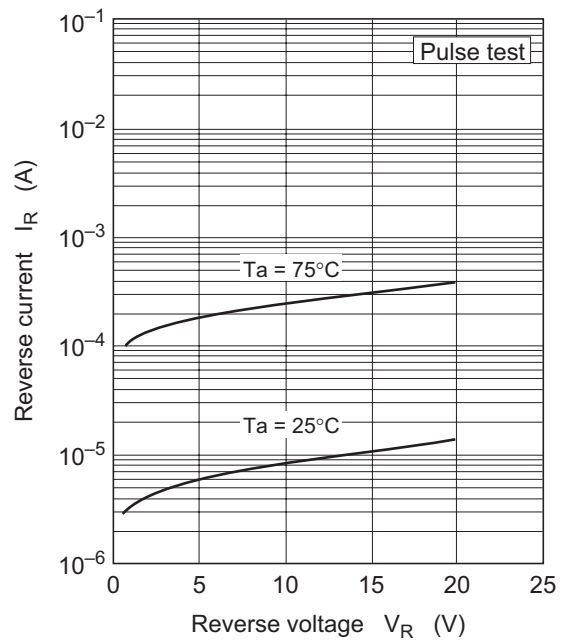


Fig.2 Reverse current vs. Reverse voltage

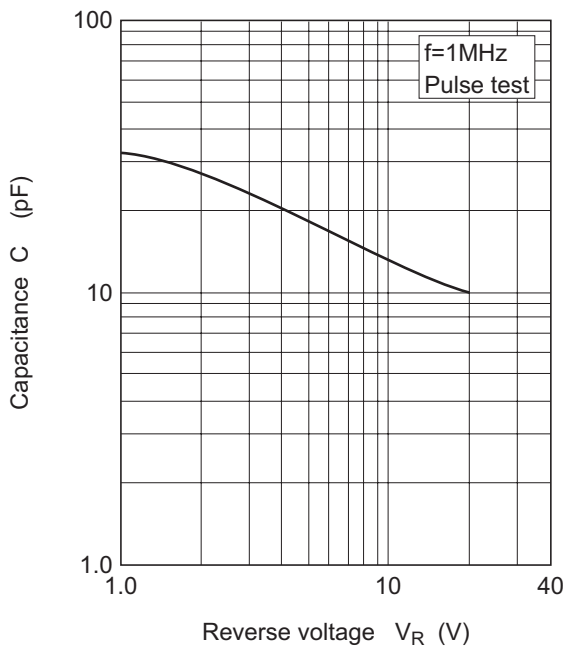


Fig.3 Capacitance vs. Reverse voltage

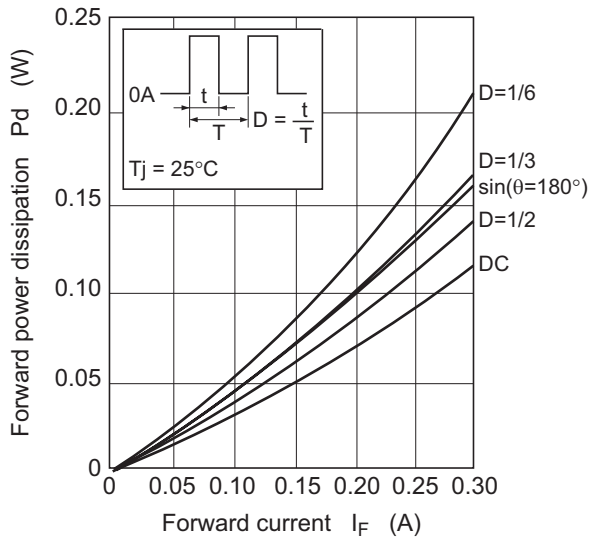


Fig.4 Forward power dissipation vs. Forward current

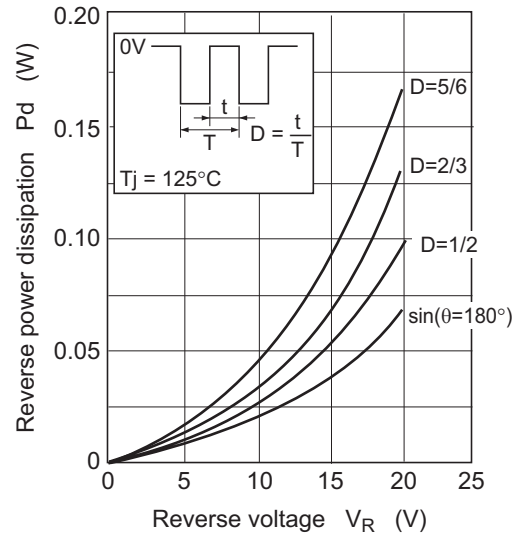


Fig.5 Reverse power dissipation vs. Reverse voltage

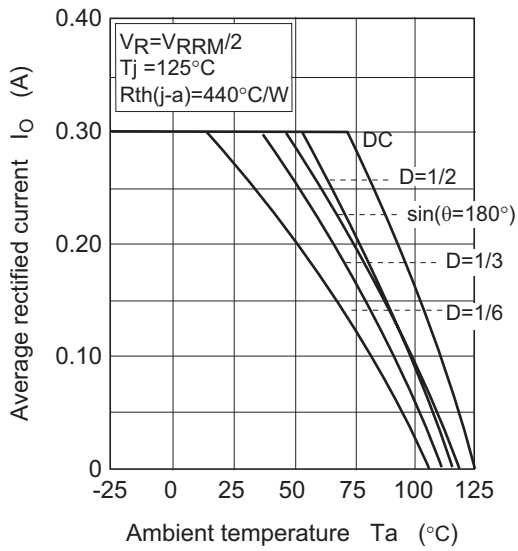
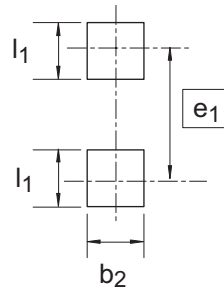
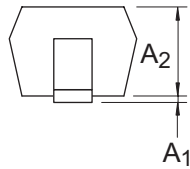
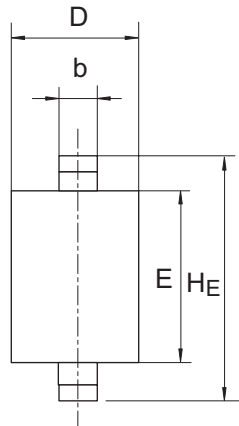


Fig.6 Average rectified current vs. Ambient temperature

Package Dimensions

Package Name	JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
URP	SC-76A	PTSP0002ZA-A	URP / URPV	0.004g



Pattern of terminal position areas

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
A <sub>1</sub>	0	-	0.1
A <sub>2</sub>	0.75	0.90	1.05
b	0.15	0.30	0.45
D	1.10	1.25	1.40
E	1.55	1.70	1.85
H <sub>E</sub>	2.35	2.50	2.65
b <sub>2</sub>	-	0.80	-
e <sub>1</sub>	-	2.30	-
l <sub>1</sub>	-	0.80	-

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